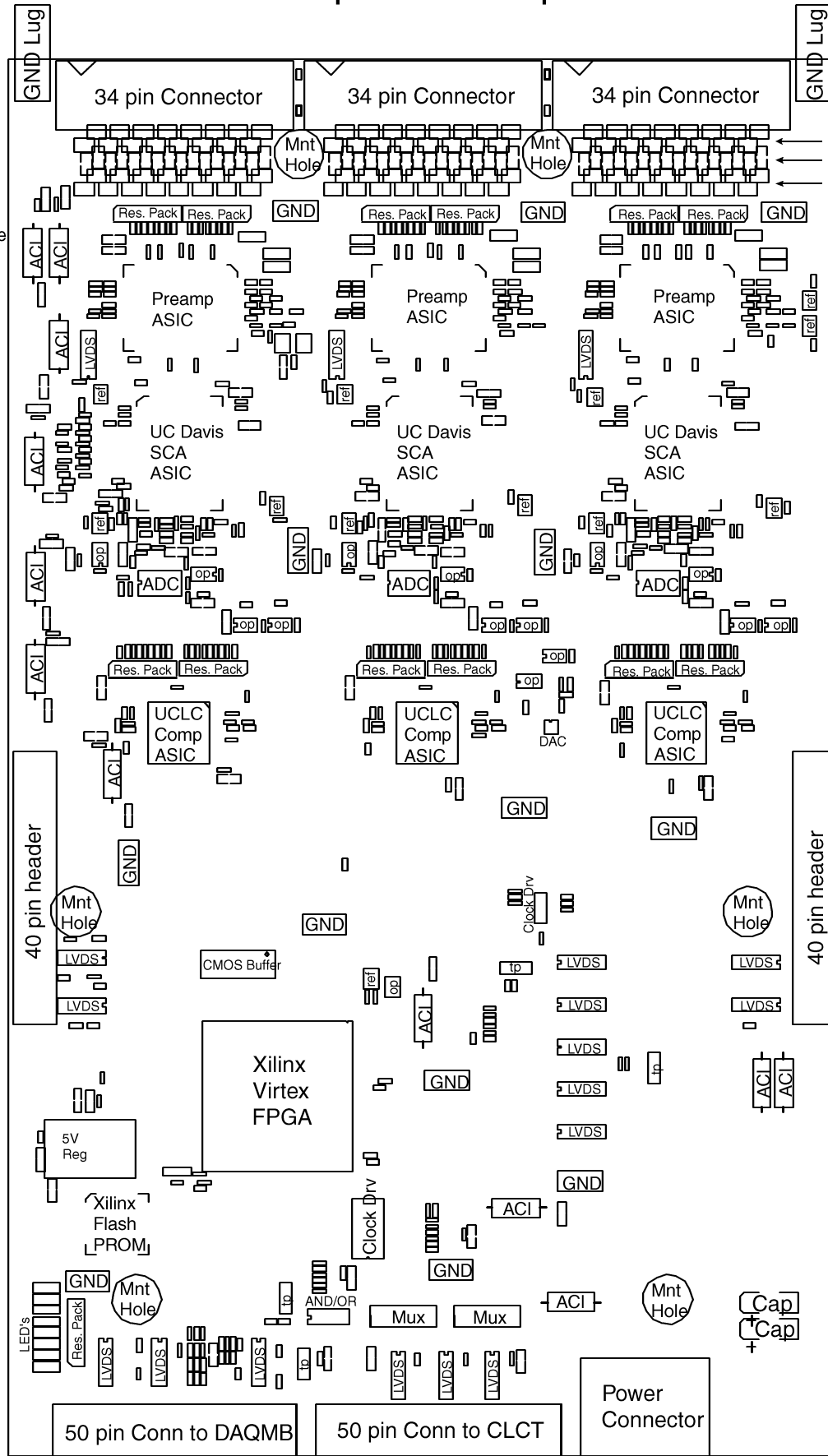


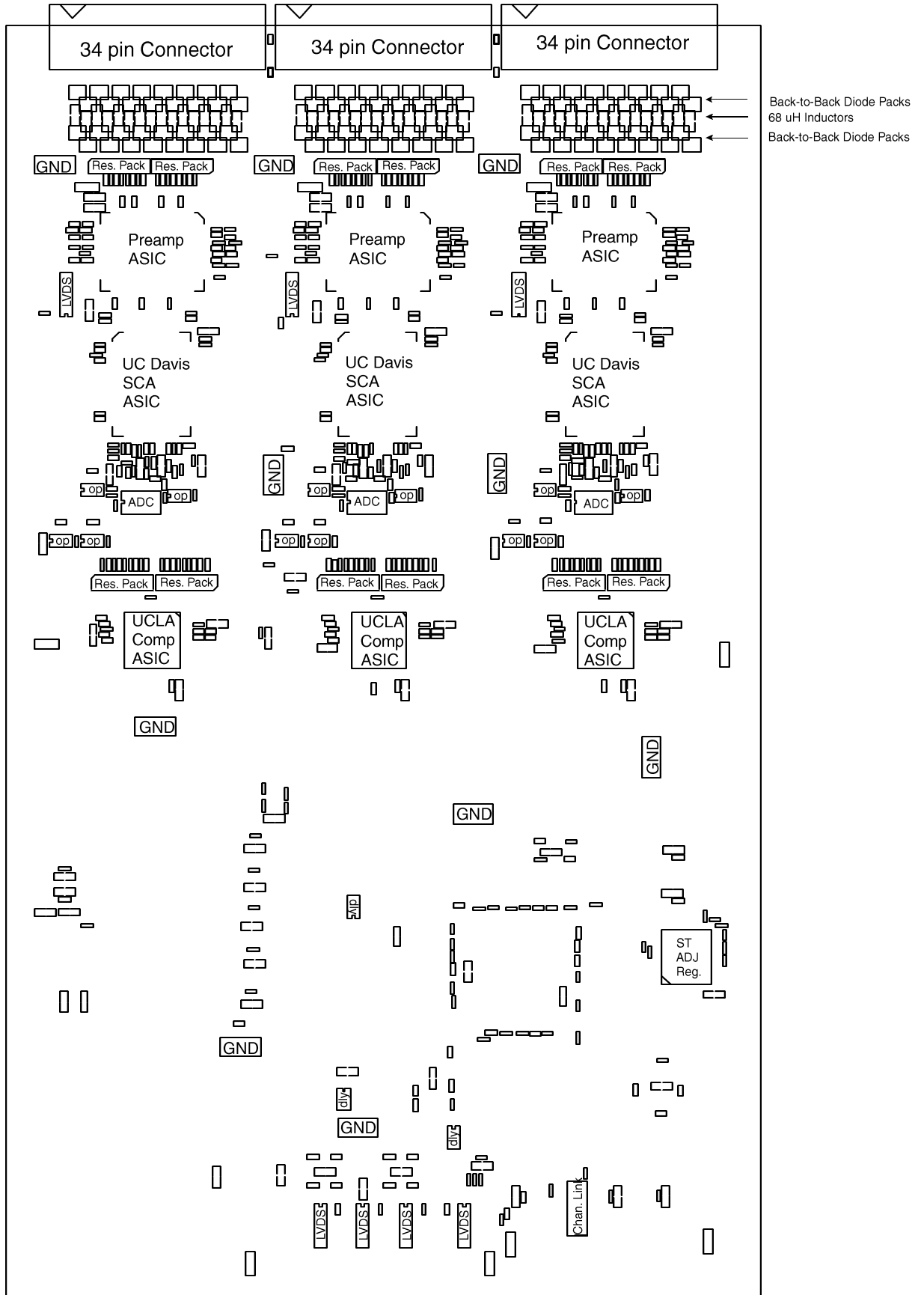
CFEB Top Side Components

ACI = Air Core Inductor
 DLY = Delay Chip
 tp = test point
 op = OpAmp
 ref = Voltage Reference



Back-to-Back Diode Packs
 68 uH Inductors
 Back-to-Back Diode Packs

CFEB Bottom Side Components



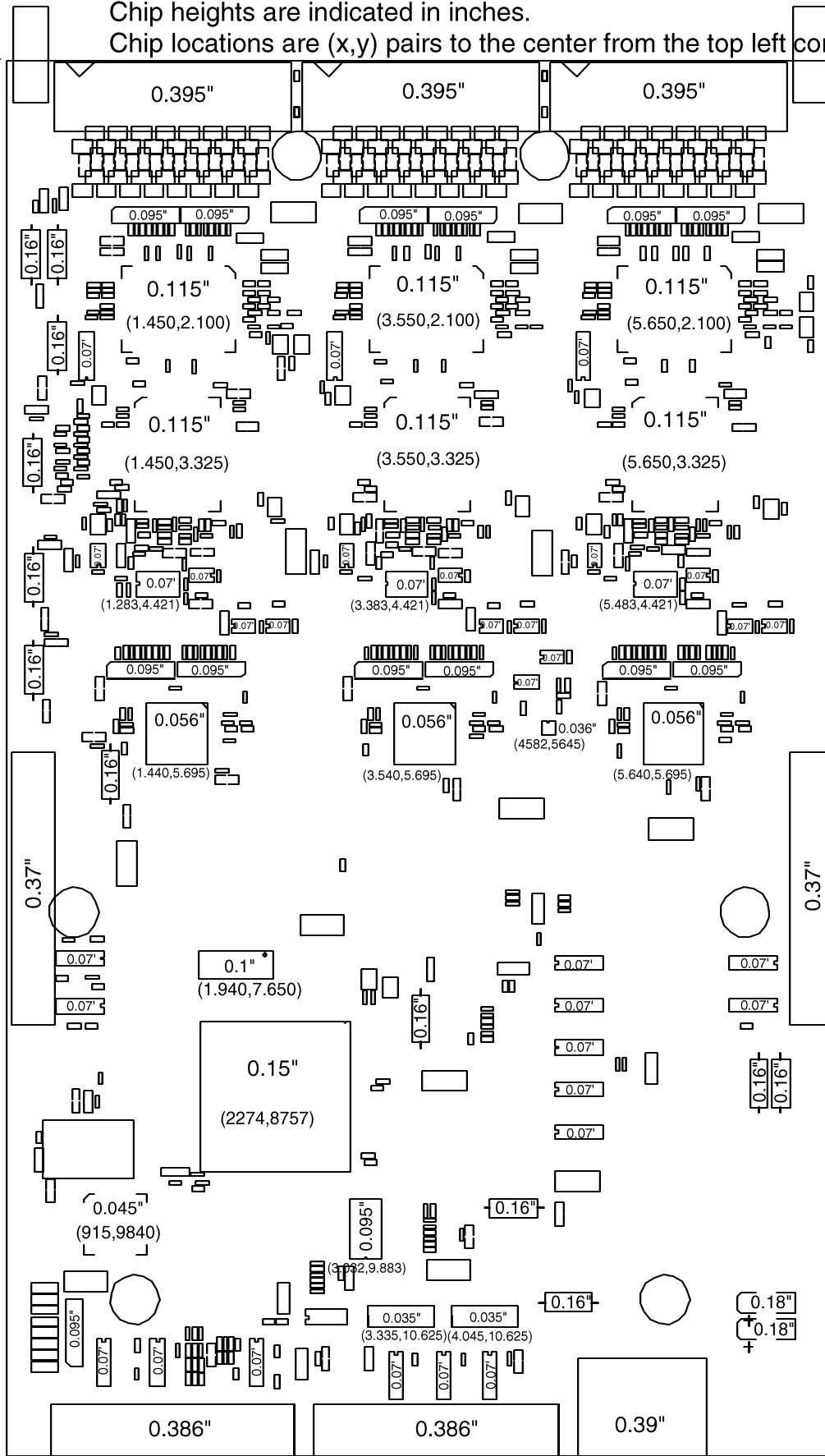
CFEB Rev8 Top Components

As Viewed from the Top

Chip heights are indicated in inches.

Chip locations are (x,y) pairs to the center from the top left corner

Positions are
referenced from
this corner. →

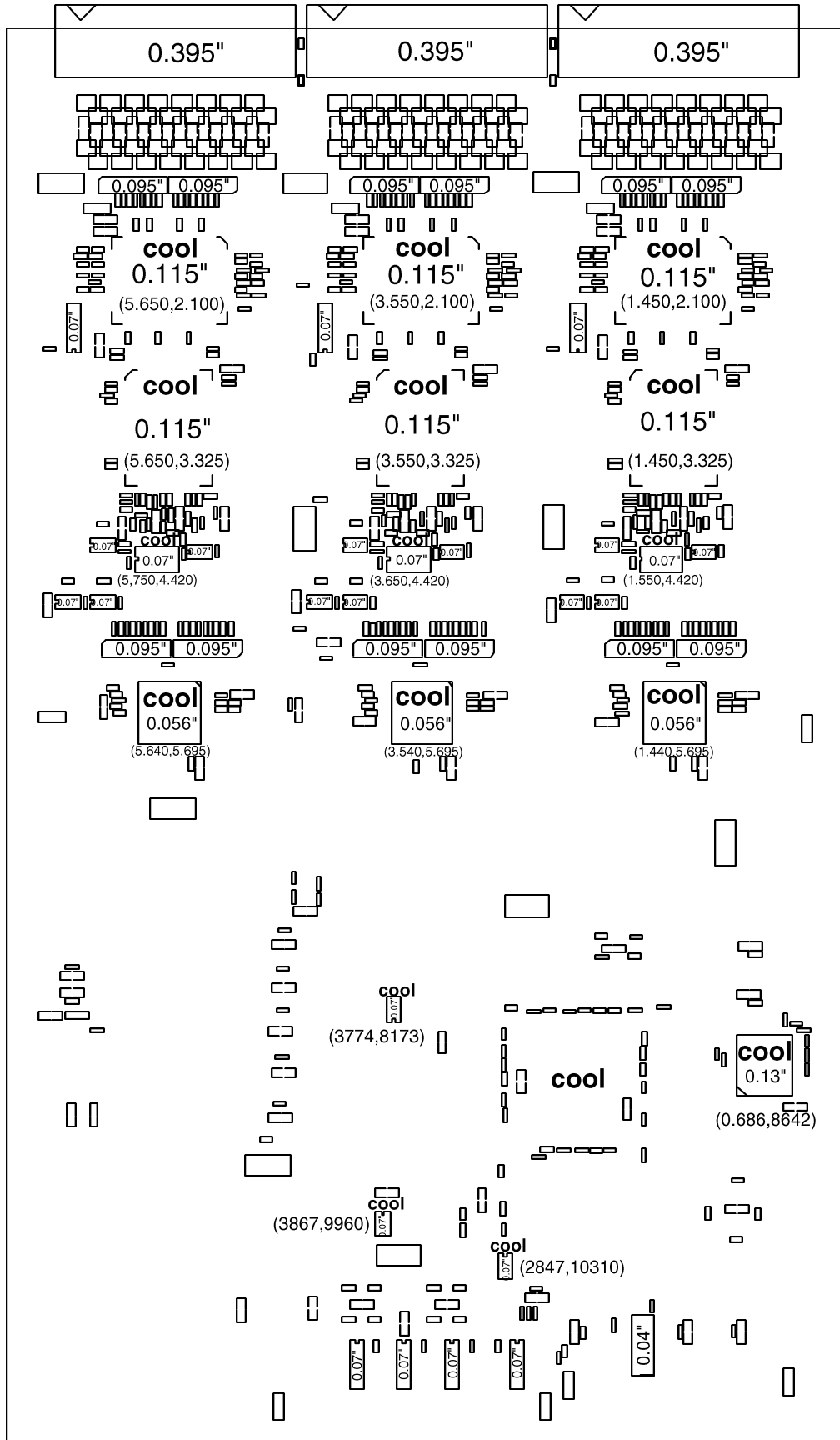


CFEB Rev8 Bottom Components As Viewed from the Bottom

Positions are referenced from this corner.

Chip heights are indicated in inches.

Chip locations are (x,y) pairs to the center of the chip measured from the top right corner.



Note: Chips that are required to be in thermal contact with the cooling plate through thermal pads are indicated with "cool".